

montblanc-project.eu | @MontBlanc\_EU

# Paving the way to a scalable, modular and power-efficient European HPC processor

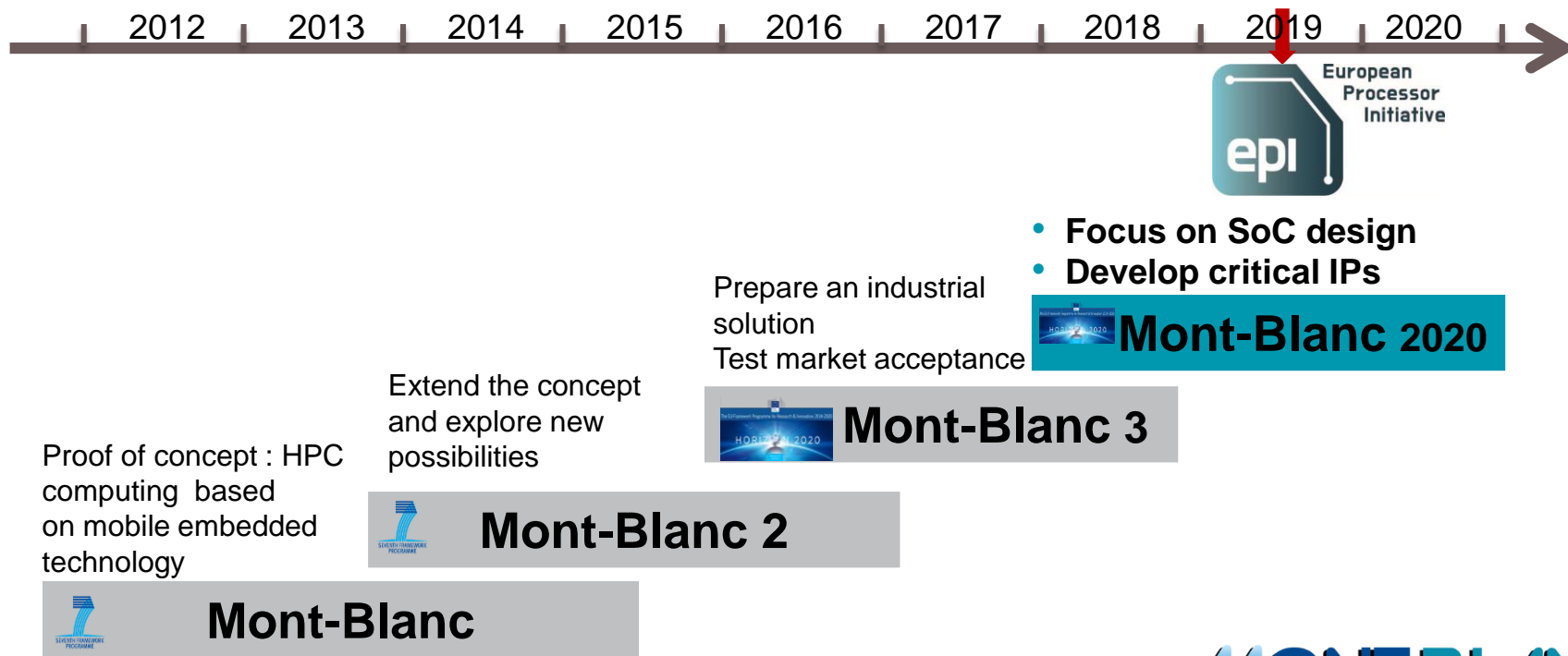
Arm HPC User's Group @ISC'19

Said Derradji (Atos)



# Mont-Blanc roadmap

**Vision:** leverage the fast growing market of mobile technology for scientific computation



# Mont-Blanc 2020 partners

Atos arm



KALRAY



JÜLICH  
FORSCHUNGSZENTRUM



→ **Trigger the development of the next generation of industrial processor for Big Data and High Performance Computing**

→ **Mont-Blanc DNA**

- economic sustainability
- power efficiency
- heterogeneity
- strong codesign approach for real applications
- building a prototype

# Mont-Blanc prototypes

2015

2016

2017

2018

2019

2020

## Mont-Blanc prototype



1080 Dual Cortex-A15 (+ Mali)

❖ 2160 Armv7 cores

## Dibona



48 nodes bi-socket THX2

❖ 3072 Armv8 cores

## MB2020 Demonstrator



Only one MB2020 SoC

❖ 32 SVE cores

# Mont-Blanc Dibona open to more users

## → The Mont-Blanc Dibona prototype:

- 48 nodes bi-socket THX2 @2GHz (3072 cores)
- 12.3 TB RAM
- featuring Mellanox EDR 100Gb/s
- Theoretical peak performance of > 49 Tflops

## → Usage:

- +70 users
- Allocations with SLURM (including bash): 15k
- Application executions with SLURM: 12.5k
- Multi-node jobs with SLURM: ~5.7k

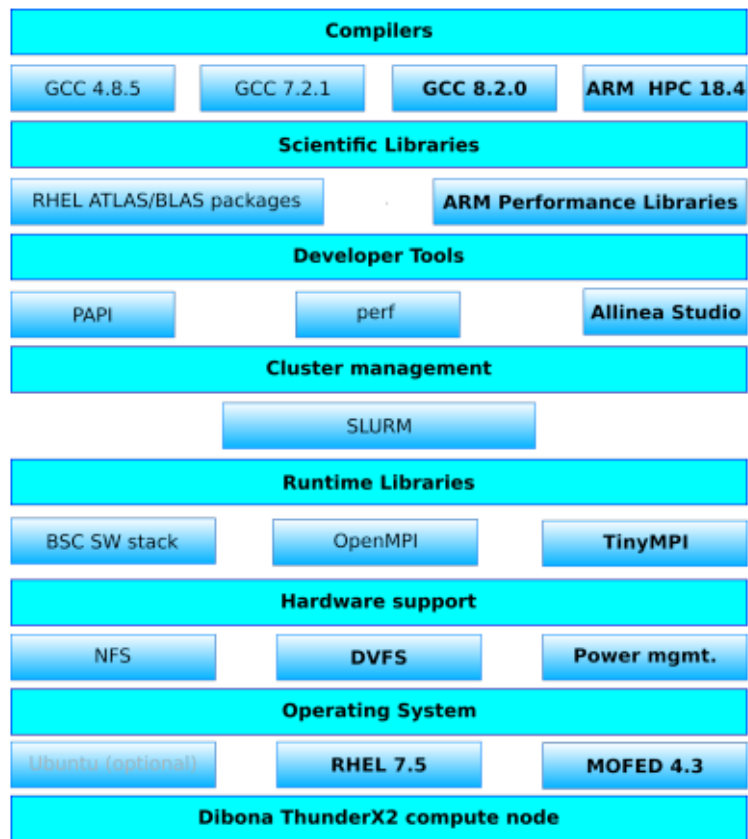
## → Events:

- Hackathon by Arm @SC18 +40 users
- Hackathon by BSC Feb. 21st +30 students



**MONT-BLANC**

# Dibona SW stack today



- ▶ Atos ARM Lab still updating the SW stack providing more OpenMPI flavors
- ▶ ARM provides new Compiler, Performance Libraries
- ▶ HW support :Atos fine grain power monitoring, DVFS
- ▶ RedHat: More recent and optimized kernel
- ▶ Mellanox: Improved drivers
- ▶ Preparing the porting/developing of Atos BXI drivers on Arm



# Introducing BullSequana XH2000



Atos is the industrial pivot of Mont-Blanc project  
ARM is one of the Bull strategic directions for the next years  
Europe is sponsoring ARM development

using best in class CPU/GPU/FPGA



using standard and proprietary interconnects

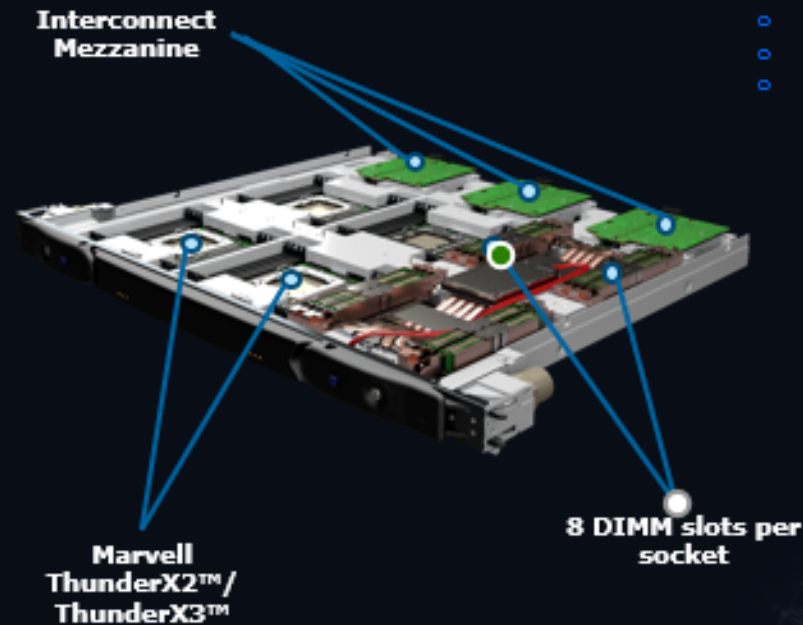




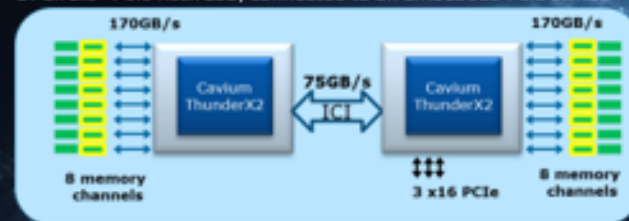


## BullSequana XH2000 Blades

BullSequana X1310: Marvell ThunderX2™/ThunderX3™ (ARMv8) processor



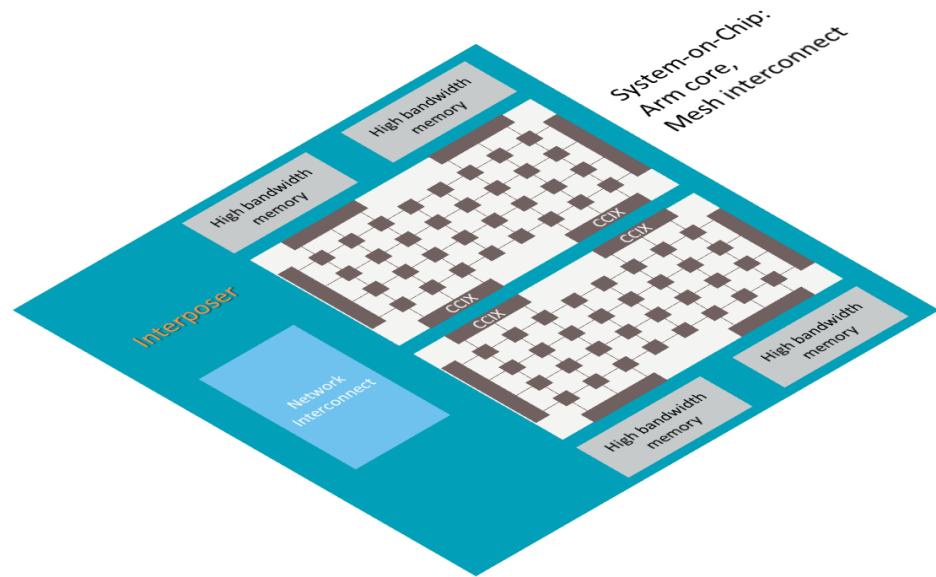
- 1U form factor
- Direct liquid cooling
- 3 compute nodes per blade with:
  - 2 Marvell ThunderX2/ThunderX3 processors with
    - Up to 32 custom ARMv8 cores per CPU, 4 threads per core, up to 2.5GHz
  - 16 DDR4 @2666MT/s DIMM slots
  - 1 Interconnect mezzanine board (High-speed Ethernet, InfiniBand EDR, HDR or HDR100)
  - 1 optional PCIe switch mezzanine
  - Disks
    - 1 x 2.5" 7 mm SATA SSD
    - Or 1x 2.5" PCIe flash SSD, connected to an embedded PCIe switch



# Project Objectives

Mont-Blanc 2020 will provide new IPs, such as a new low-power “Network-on-Chip” based on the Coherent Hub Interface (CHI) architecture:

- supporting up to 128 SVE cores;
- each core embedding 2 vector units from 128 to 1024 bits wide;
- interfacing HBM2/3 memory controllers to sustain high memory bandwidth.



### 3 Key Challenges

To achieve the desired performance with the targeted power consumption, the project will need to:



understand the trade-offs between vector length, NoC bandwidth and memory bandwidth to maximize processing unit efficiency;



come up with an innovative on-die interconnect that can deliver enough bandwidth with minimum energy consumption;



opt for a high-bandwidth / low power memory solution with enough capacity and bandwidth for Exascale applications.

- **To use the ARM ISA**
- **To design, implement and leverage new technologies to improve the performance, power efficiency, reliability and security of the processor :**
  - large SVE compute units
  - specific NoC
  - specific High Bandwidth Memory controller
  - specific SoC Power Management controller
  - innovative packaging technologies (Interposer)
  - state of the art silicon process 7nm FF
- **To improve on the economic sustainability of processor development through a modular design that allows to retarget our SoC for different markets adding specific accelerators.**

# From design to HW emulation

- **Objectives:** verification of MB2020 design (interconnection network and memory hierarchy) and performance extractions
- **Methodology:** emulation of the MB2020 design with applicative workflow based on simulation traces injected into the design
  - Trace injector are playing the role of ARM cores in the design



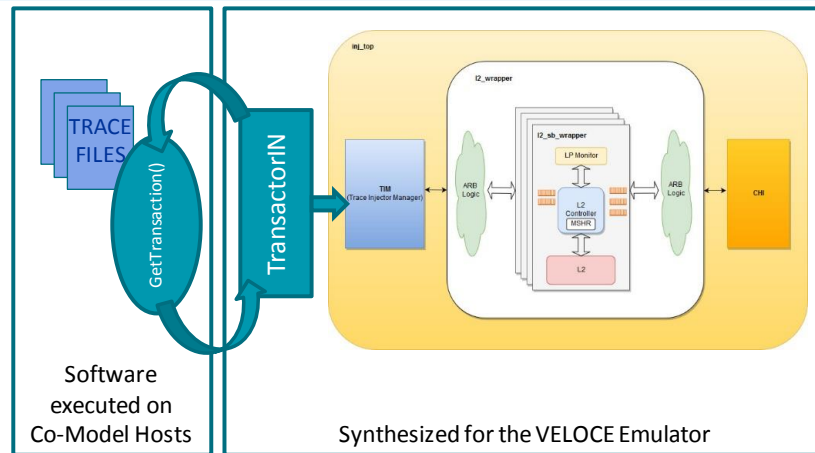
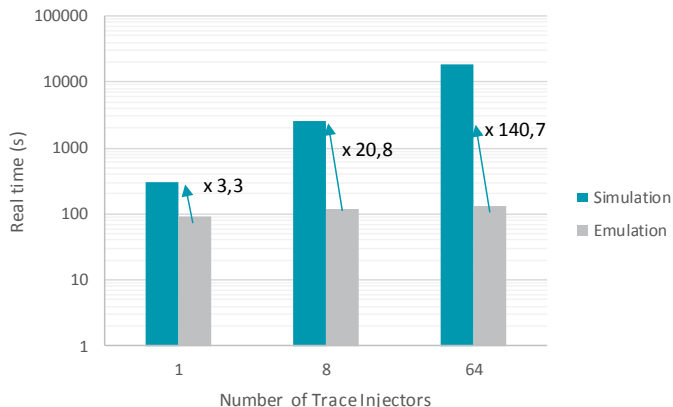
Mentor Graphics Veloce2: Powerful emulator environment hosted by CEA

- Up to 2MHz emulation speed
- 200 Mbytes max capacity
- 32 Gb memory capacity

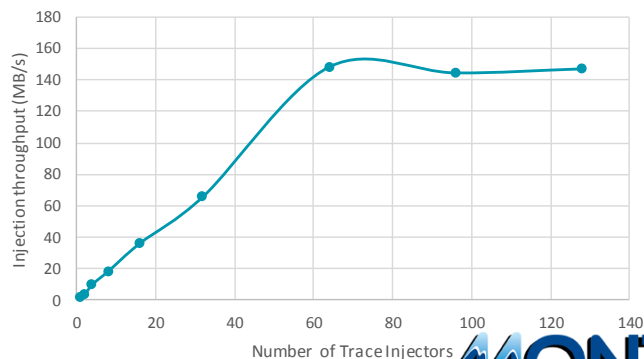
# HW emulator accelerated simulation

- **Validation of the trace injector design on the emulator**
  - HW/SW interface for trace file injection in the emulator
  - RTL code fully synthesizable for the HW part
  - Configurable number of Trace Injectors
- **Measurement of emulation performance compared to simulation**
- **Measurement of aggregated injection throughput during the emulation**
- **Emulation environment ready to integrate the MB2020 design**

RTL simulation time compared to emulation time  
for the same design

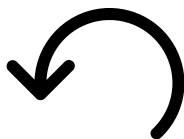


Aggregated injection throughput during the emulation



# Codesign from Apps to architecture

setting NoC parameters  
evaluate performance using traces  
identify HW bottleneck  
then try new parameters or new features

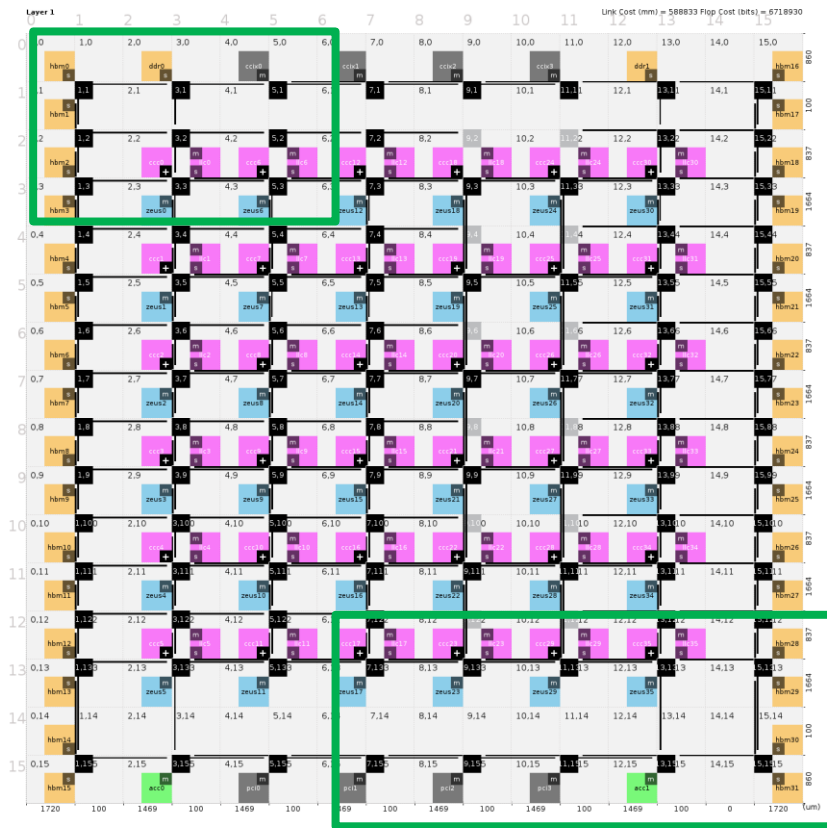


**Message class/BW:** the CHI coherence protocol is mapped over several physical layers:

- Data, Response, Request, Snoop
- Each message class can be mapped to several lanes to sustain the BW required per channel

**Memory mapping/affinity :**

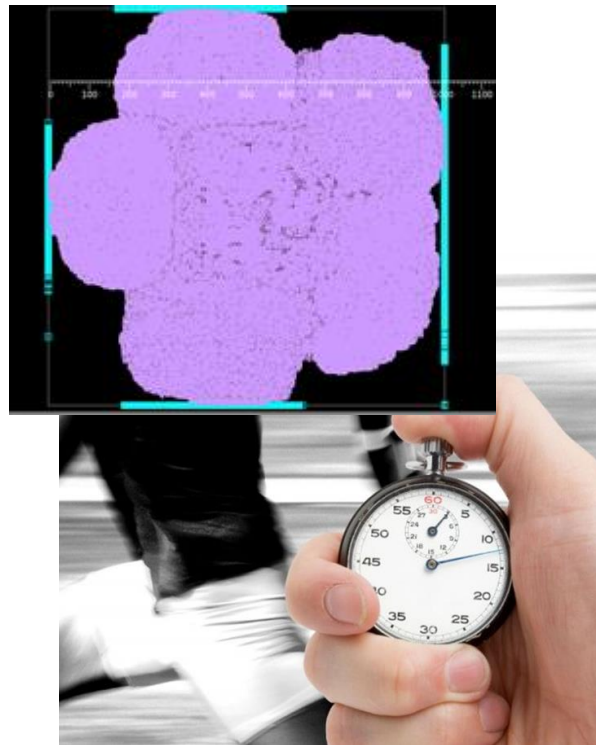
- the home agent/snoop filter must be distributed
- the interleaving function (per group per cache line) must assure well-balanced traffic spreading to memory (home agents and controllers).





# Demonstrating the performance

- **Power, Performance and Area (PPA) metrics in 7nm**
- **Using IP RTL, back-end design team will run topographical synthesis (=taking physical info into account) using Design Compiler NXT from Synopsys**
- **Providing estimations for all IPs, including SVE cores**



# Beyond Mont-Blanc 2020

- Mont-Blanc 2020 is at the heart of the European exascale supercomputer effort
- Most of the **IP developed within Mont-Blanc 2020** will be reused and productized in the European Processor Initiative (EPI)



# MONT-BLANC 2020

**More information:**  
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